



your BEST camera module partner

KLT-MFA55-AR1335 V1.0 NL

13MP OnSemi AR1335 PLCC MIPI Interface M12 Fixed Focus Camera Module No Lens





Front View

Back View

Specifications

Camera Module No.	KLT-MFA55-AR1335 V1.0 NL		
Resolution	13MP		
Image Sensor	AR1335_PLCC		
Sensor Type	1/3.2"		
Pixel Size	1.1 um x 1.1 um		
Pixel	4208 x 3120		
Module Size	50.00 x 20.00 mm		
Module Type	Fixed Focus		
Interface	MIPI		
Fixed Focus VCM Driver IC	None		
Lens Type	No Lens		
Operating Temperature	-30°C to +70°C		
Mating Connector	DF30FC-30DS-0.4V		

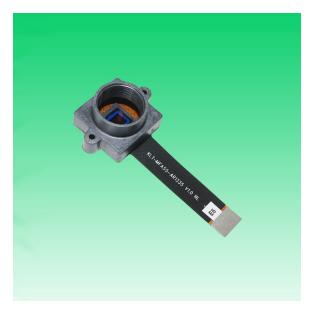




your BEST camera module partner

KLT-MFA55-AR1335 V1.0 NL

13MP OnSemi AR1335 PLCC MIPI Interface M12 Fixed Focus Camera Module No Lens



Top View



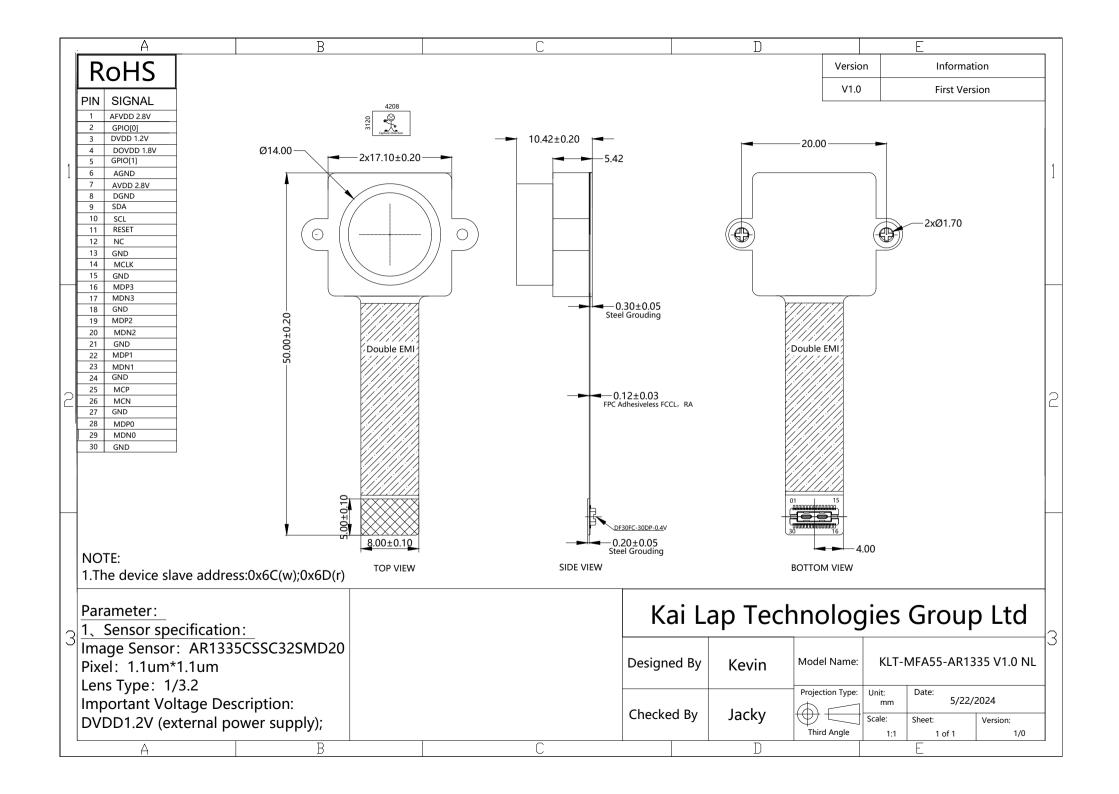
Side View



Bottom View



Mating Connector





Product Overview

AR1335: 13 MP 1/3" CMOS Image Sensor

For complete documentation, see the data sheet.



The AR1335 is a 1/3.2-inch CMOS active-pixel digital image sensor with a pixel array of 4208H x 3120V. The AR1335 digital image sensor, features breakthrough 1.1 m pixel technology that delivers superior low-light image quality through leading sensitivity, quantum efficiency and linear full well. This allows image quality that rivals digital still cameras. With a sensor architecture focused on low power and a high Chief Ray Angle (CRA) for low Z-heights, the AR1335 is ideal for smartphone and other mobile device applications. It incorporates sophisticated on-chip camera functions such as windowing, mirroring, column and row skip modes, and snapshot mode. It is programmable through a simple two-wire serial interface. The AR1335 sensor can generate full resolution image at up to 30 frames per second (fps) and supports advanced video modes including 4K 30fps, 1080P 60fps and 720P 120fps.

Features

- 13MP CMOS sensor with advanced 1.1µm pixel BSI technology
- · Data interfaces: 2,3 and 4 lane MIPI
- Bit-depth compression available for MIPI: 10-8 and 10-6 to lower bandwidth
- · 3D synchronization controls to enable stereo video capture
- 6.8 kbits one time programmable memory (OTPM)
- Programmable controls: gain, horizontal and vertical blanking, auto black level offset correction, frame size/rate, exposure, leftright and top-bottom image reversal, window size, and panning
- Two on-die phase-locked loop (PLL) oscillators for super low noise performance
- · On-chip temperature sensor
- · Bayer pattern horizontal down-size scaler
- Simple two-wire fast-mode+ serial interface For more features, see the data sheet

Applications

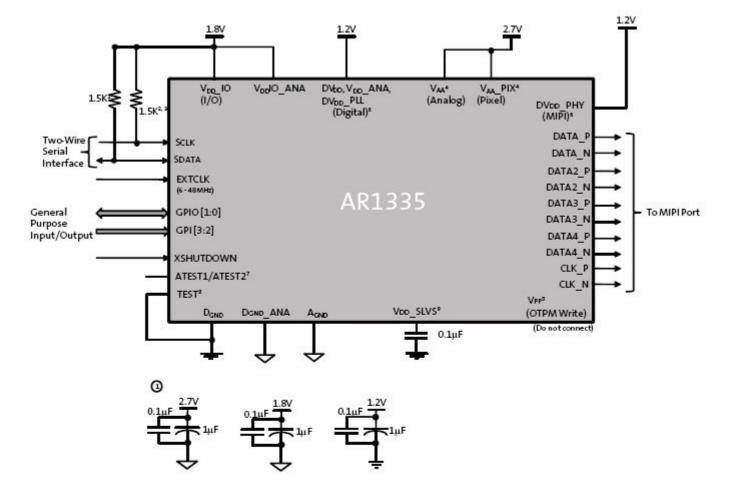
- Mobile
- · 4K video capture
- High resolution still capture

End Products

- · Smart Phone
- Digital Still Camera
- PC Camera
- Consumer devices

Part Electrical	Specifica	tions									
Product	Compliance	Status	Туре	Megapixel s	Frame Rate (fps)	Optical Format	Shutter Type	Pixel Size (µm)	Output Interface	Color	Package Type
AR1335CSSC11SMD2 0	Pb-free Halide free	Active	CMOS	13	30	1/3.2 inch	Electronic Rolling	1.1 x 1.1	MIPI	RGB	
AR1335CSSC11SMKA 0-CP	Pb-free Halide free	Active	CMOS	13	30	1/3.2 inch	Electronic Rolling	1.1 x 1.1	MIPI	RGB	ODCSP- 63
AR1335CSSC11SMKA 0-CR	Pb-free Halide free	Active	CMOS	13	30	1/3.2 inch	Electronic Rolling	1.1 x 1.1	MIPI	RGB	ODCSP- 63
AR1335CSSC32SMD2 0	Pb-free Halide free	Active	CMOS	13	30	1/3.2 inch	Electronic Rolling	1.1 x 1.1	MIPI	RGB	
AR1335CSSM11SMD2 0	Pb-free Halide free	Active	CMOS	13	30	1/3.2 inch	Electronic Rolling	1.1 x 1.1	MIPI	RGB	
AR1335CSSM32SMD2	Pb-free Halide free	Active	CMOS	13	30	1/3.2 inch	Electronic Rolling	1.1 x 1.1	MIPI	RGB	

Application Diagram



For connectivity above:

Notes: 1. All power supplies should be adequately decoupled; recommended cap values are:

- 2.7V: 1.0μF and 0.1μF
- 1.2V: 1.0uF and 0.1μF
- 1.8V: 1.0uF and 0.1μF
- 2. Resistor value 1.5kΩ is recommended, but may be greater for slower two-wire speed.
- 3. This pull-up resistor is not required if the controller drives a valid logic level on SCLK at all times.
- 4. VAA and VAA PIX must be tied together.
- 5. Internal charge pump is used for OTPM programming.
- 6. Digital and MIPI supply can be tied together.
- 7. ATEST1/ATEST2 must be left floating.
- 8. TEST pin must be tied to DGND.
- VDD_SLVS must be connected to DGND through a bypass cap (0.1uF).

For more information please contact your local sales support at www.onsemi.com.

Created on: 9/30/2017





1/3.2-Inch 13 Mp CMOS Digital Image Sensor

AR1335 Datasheet, Rev. A

For the latest datasheet, please visit: www.aptina.com

Features

- 13 Mp CMOS sensor with advanced 1.1 μm pixel BSI technology
- Data interfaces: two-, three-, and four-lane serial mobile industry processor interface (MIPI)
- Bit-depth compression available for MIPI Interface: 10-8 and 10-6 to enable lower bandwidth receivers for full frame rate applications
- 3D synchronization controls to enable stereo video capture
- 6.8 kbits one-time programmable memory (OTPM) for storing shading correction coefficients and module information
- Programmable controls: gain, horizontal and vertical blanking, auto black level offset correction, frame size/rate, exposure, left-right and top-bottom image reversal, window size, and panning
- Two on-die phase-locked loop (PLL) oscillators for super low noise performance
- On-chip temperature sensor
- Bayer pattern horizontal down-size scaler
- Simple two-wire fast-mode+ serial interface
- · Low dark current
- Interlaced multi-exposure readout enabling High Dynamic Range (HDR) still and video applications
- On-chip lens shading correction
- Support for external mechanical shutter
- Support for external LED or Xenon Flash
- Extended Flash duration up to start of frame readout

Applications

- Cellular phones
- · Digital still cameras
- PC cameras
- PDAs

Table 1: Key Performance Parameters

Paramet	er	Value			
Optical f	ormat	1/3.2 -inch 13 Mp (4:3)			
Active pixels		4208H x 3120V			
Pixel size		1.1μm Back Side Illuminated (BSI)			
Chief ray	angle (CRA)	32°			
Die size		6.3 mm x 5.7 mm			
Input clo	ck frequency	6 - 48 MHz			
Interface	2	4-lane MIPI (2- and 3-lane supported); Max data rate: 1.2Gbps/lane			
Subsampling modes (column and row)		skip2 bin2 skip3 bin3 skip4 bin4 skip2bin2			
ADC reso	olution	10 bits, on-die			
Analog g	gain	1x - 7.75x			
Digital g	ain	Up to 7.98x			
Scaler		Adjustable scaling up to 8x			
Tempera	ture sensor	10-bit, controlled by two-wire serial I/F			
Compres	sion	DPCM: 10-8-10, 10-6-10			
3D supp	ort	Frame rate and exposure synchronization			
Supply	VAA, VAA_PIX				
voltage	VDD_IO, VDDIO_ANA	1.7 - 1.9 V (1.8 V nominal)			
VDD, VDD_ANA, VDD_PLL, VDD_PHY		1.14 - 1.3 V (1.2 V nominal)			
Power consumption		270 mW at 60°C (TYP) at 13 Mp 30 fps			
Responsivity		4700 e ⁻ /lux-sec			
SNRMAX		37 dB			
Dynamic	Range	69 dB			
Operatin		-30°C to +70°C			
	ture Range				
(at junct	ion) - IJ				



AR1335: 1/3.2-Inch 13Mp CMOS Digital Image Sensor Ordering Information

Table 2: **Mode of Operation and Power**

Mode	Resolution Readout Configuration		HFOV	FPS	Power Consumption [mW]
		4:3 Snapshot Mode			
13 M full resolution	4208x3120	13M full mode	100%	30	270
13 M full resolution	4208x3120	13M full mode	100%	24	250
VGA	640 x 480	Crop+Subsampling+Scaling	61%	120	190
QVGA	320 x 240	Crop+Subsampling+Scaling	30%	240	165
16:9 Video Mode 30 FPS					
4K UHD	3840 x 2160	Cropping	91%	30	230
4K Cinema	4096 x 2160	Cropping	97%	30	235
1080p	1920 x 1080	Crop+Subsampling+Scaling	91%	30	160
1080p LP	1920 x 1080	Crop+Subsampling+Scaling	91%	30	135
720p	1280 x 720	Crop+Subsampling+Scaling	91%	30	140
		16:9 Video Mode 60 FPS			
1080p	1920 x 1080	Crop+Subsampling+Scaling	91%	60	210
1080p LP	1920 x 1080	Crop+Subsampling+Scaling	91%	60	180
720p	1280 x 720	Crop+Subsampling+Scaling	91%	60	175
		3M 30 FPS			
3M	2000 x 1500	Crop+Subsampling+Scaling	95%	30	195
3M LP	2000 x 1500 Crop+Subsampling+Scaling		95%	30	170
		16:9 Video Mode 120 FPS			
720p	1280 x 720	Crop+Subsampling+Scaling	91%	120	260

Ordering Information

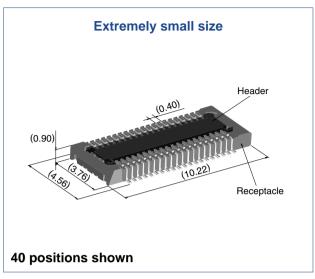
Available Part Numbers Table 3:

Part Number	Description
AR1335CSSC32SMD20	Bare die

0.4 mm Pitch, 0.9 mm Height, Board-to-Board / Board-to-FPC Connectors

DF30 Series





Overview

Continuous miniaturization and increased component density on PCB created demand for extremely low profile connectors. This series is addition of a new extremely low profile connectors to Hirose's wide range of high reliability board-to-board/board-to-FPC connection solutions.

Features

1. Contact reliability

Concentration of the contact's normal forces at the single point assures good contact wipe and electrical reliability, while confirming the fully mated condition with a definite tactile click.

2. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces the connectors will self align in horizontal axis within 0.3 mm.

3. Automatic board placement

Packaged on tape-and-reel the plug and headers have sufficiently large flat areas to allow pick-up with vacuum nozzles of automatic placement equipment.

4. Variety of contact positions and styles

Available in standard contact positions of: 20, 22, 24, 30, 34, 40, 50, 60, 70 and 80 with and without metal fittings. Addition of metal fittings does not affect external dimensionsof the connectors.

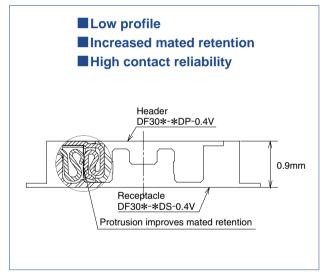
Smaller contact positions are also available.

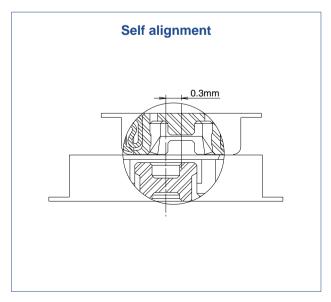
5. Support for continuity test connector

Connectors which have increased insertion and removal durability are available for continuity tests. Contact your Hirose sales representative for details.

Applications

Cellular phones, PDA's, mobile computers, digital cameras, digital video cameras, and other devices demanding high reliability connections in extremely limited spaces.





■Product Specifications

Datina	Rated current 0.3A	Operating temperature range	: -35°C to 85°C (Note 1)	Storage temperature range	-10°C to 60°C (Note 2)
Rating	Rated voltage 30V AC	Operating humidity range	: Relative humidity 20% to 80%	Storage humidity range	Relative humidity 40% to 70% (Note 2)

Item	Specification	Conditions		
1. Insulation resistance	50 MΩ min.	100V DC		
2. Withstanding voltage	No flashover or insulation breakdown.	100V AC / one minute		
3. Contact resistance	100 mΩ max.	100 mA		
4. Vibration	No electrical discontinuity of 1 μ s or more	Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 2 hours, 3 axis		
5. Humidity	Contact resistance: 100 m Ω max. Insulation resistance: 25 M Ω min.	96 hours at temperature of 40°C±2°C and RH of 90% to 95%		
6. Temperature cycle	Contact resistance: 100 m Ω max. Insulation resistance: 50 M Ω min.	Temperature: $-55^{\circ}C \rightarrow +5^{\circ}C$ to $+35^{\circ}C \rightarrow +85^{\circ}C \rightarrow +5^{\circ}C$ to $+35^{\circ}C$ Duration: $30 \rightarrow 10 \rightarrow 30 \rightarrow 10$ (Minutes) 5 cycles		
7. Durability (insertions/withdrawals)	Contact resistance: 100 mΩ max.	50 cycles(Connector for conductivity tests: 500 cycles)		
8. Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 300°C for 3 seconds		

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating temperature range and humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

■Materials and Finishes

Connectors	Component	Material	Finish	Remarks
Receptacles	Insulator	LCP	Color : Black	UL94V-0
and	Contacts	Phosphor bronze	Gold plated	
Headers	Metal fittings	Phosphor bronze	Tin-cupper plated	

■Ordering information

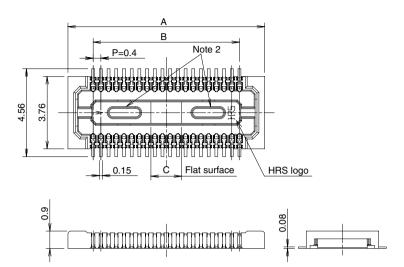
Receptacles and Headers

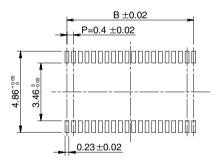
DF30	FC -	*	DS -	0.4	V	(**)
<u> </u>	2	6	4	6	6	7

1 Series name: DF30	6 Contact pitch: 0.4 mm
2 Configuration	6 Termination section
FB: With metal fittings, without bosses	V: Straight SMT
FC: Without metal fittings, without bosses	Packaging
CJ: Connector for conductivity tests	(81): Embossed tape packaging (5,000 pieces per reel)
3 Number of positions: 20, 22, 24, 30, 34, 40, 50, 60, 70, 80	(82): Embossed tape packaging (1,000 pieces per reel)
4 Connector type	
DS: Double row receptacle	
DP: Double row header	

■Receptacles (without metal fittings)







Recommended solder paste thickness: 120 μm

[Specification number] -**, (**)
(81): Embossed tape packaging (5,000 pieces per reel)

* Tolerances non- accumulative.

Unit: mm

Part Number	CL No.	Number of contacts	А	В	С
DF30FC-20DS-0.4V(**)	CL684-1109-8-**	20	6.22	3.6	1.2
DF30FC-22DS-0.4V(**)	CL684-1110-7-**	22	6.62	4.0	1.2
DF30FC-24DS-0.4V(**)	CL684-1111-0-**	24	7.02	4.4	1.2
DF30FC-30DS-0.4V(**)	CL684-1112-2-**	30	8.22	5.6	1.2
DF30FC-34DS-0.4V(**)	CL684-1113-5-**	34	9.02	6.4	1.36
DF30FC-40DS-0.4V(**)	CL684-1078-6-**	40	10.22	7.6	1.6
DF30FC-50DS-0.4V(**)	CL684-1114-8-**	50	12.22	9.6	2.0
DF30FC-60DS-0.4V(**)	CL684-1082-3-**	60	14.22	11.6	2.4
DF30FC-70DS-0.4V(**)	CL684-1115-0-**	70	16.22	13.6	2.8
DF30FC-80DS-0.4V(**)	CL684-1116-3-**	80	18.22	15.6	3.2

Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.





your BEST camera module partner

Cameras Applications





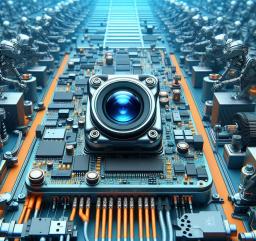


Automotive Driver Pilot

Live Streaming

Video Conference







Eye Tracker Biometric Detection

Machine Vision

Agricultural Monitor







Night Vision Security

Drone and Sports Eagle Eyes

Interactive Pet Camera





Cameras Applications

your BEST camera module partner







your BEST camera module partner

Camera Module Pinout Definition Reference Chart

ina Himax GalaxyCore PixArt SmartSens Sensors
Description
ground for digital circuit
ground for analog circuit
DVP PCLK output
power down active high with internal pull-down resistor
system input clock
reset active low with internal pull-up resistor
no connect
SCCB data
SCCB input clock
DVP VSYNC output
DVP HREF output
power for I/O circuit
power for VCM circuit
power for analog circuit
power for digital circuit
strobe output
synchronize the VSYNC signal from the other sensor
SCCB last bit ID input
mechanical shutter output indicator
frame exposure / mechanical shutter
general purpose inputs
I2C slave address select
CEN chip enable active high on VCM driver IC
3
MIPI 1st data lane negative output
MIPI 1st data lane positive output
MIPI 2nd data lane negative output
MIPI 2nd data lane positive output
MIPI 3rd data lane negative output
MIPI 3rd data lane positive output
MIPI 4th data lane negative output
MIPI 4th data lane positive output
MIPI clock negative output
MIPI clock positive output
,
DVP data output port 0
DVP data output port 1
DVP data output port 2
DVP data output port 3
DVP data output port 4
DVP data output port 5
DVP data output port 6
DVP data output port 7
DVP data output port 8
DVP data output port 9
DVP data output port 10
DVP data output port 11





your BEST camera module partner

Camera Reliability Test

	Reliability Inspect	ion Item	Tanting Mathad	A to u Cuito ui -	
Category		Item	Testing Method	Acceptance Criteria	
Environmental	Storage	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation	
	Temperature	Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation	
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation	
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation	
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation	
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation	
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional	
		With Package 60cm	10 Times on Wood Floor	Electrically Functional	
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional	
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional	
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional	
	Cable Tensile Strength Test Loading Weight 4 kg 60 Seconds Cycling in 24 Hours		Tensile Testing Machine	Electrically Functional	
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional	
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional	
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional	
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional	













Camera Inspection Standard

your BEST camera module partner

Inspection Item			Lanca Cara Madha d	0(
Category		Item	Inspection Method	Standard of Inspection	
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
Function	Image	No Communication	Test Board	Not Allowed	
		Bright Pixel	Black Board	Not Allowed In the Image Center	
		Dark Pixel	White board	Not Allowed In the Image Center	
		Blurry	The Naked Eye	Not Allowed	
		No Image	The Naked Eye	Not Allowed	
		Vertical Line	The Naked Eye	Not Allowed	
		Horizontal Line	The Naked Eye	Not Allowed	
		Light Leakage	The Naked Eye	Not Allowed	
		Blinking Image	The Naked Eye	Not Allowed	
		Bruise	Inspection Jig	Not Allowed	
		Resolution	Chart	Follows Outgoing Inspection Chart Standard	
		Color	The Naked Eye	No Issue	
		Noise	The Naked Eye	Not Allowed	
		Corner Dark	The Naked Eye	Less Than 100px By 100px	
		Color Resolution	The Naked Eye	No Issue	
Dimension		Height	The Naked Eye	Follows Approval Data Sheet	
		Width	The Naked Eye	Follows Approval Data Sheet	
		Length	The Naked Eye	Follows Approval Data Sheet	
		Overall	The Naked Eye	Follows Approval Data Sheet	

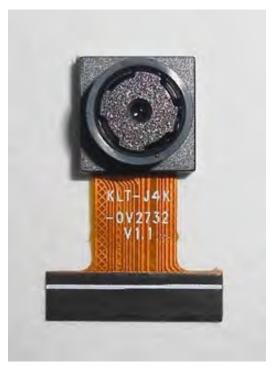




your BEST camera module partner

KLT Package Solutions

KLT Camera Module



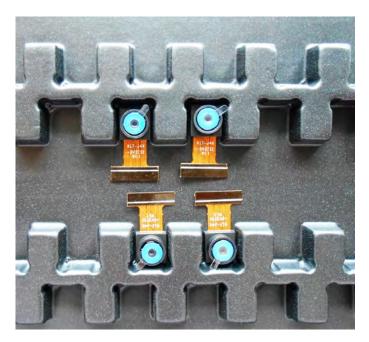
Tray with Grid and Space



Complete with Lens Protection Film



Place Cameras on the Tray







your BEST camera module partner

Camera Modules Package Solution

Full Tray of Cameras



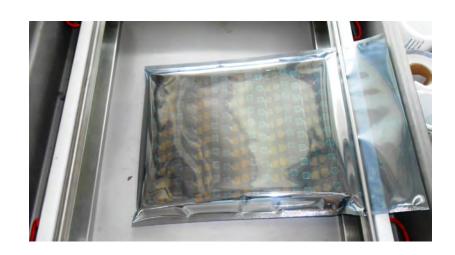
Put Tray into Anti-Static Bag



Cover Tray with Lid



Vacuum the Anti-Static Bag







your BEST camera module partner

Camera Modules Package Solution

Sealed Vacuum Bag with Labels 1. Model and Description 2. Quantity 3. Shipping Date 4. Caution







your BEST camera module partner

Large Order Package Solution

Place Foam Sheets Between Trays

Foam Sheets are Slightly Larger than Trays





Place Foam Sheets and Trays into Box

Foam Sheets are Tightly Fitting Box









your BEST camera module partner

Small Order Package Solution

Place Foam Sheets and Trays into Small Box

Foam Sheets are Nicely Fitting the Small Box





Package in Small Box for Shipment

Place Small Boxes into Larger Box









your BEST camera module partner

Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box





Carbon Box Ready for Shipment 1. Delivery Address and Phone No. 2. Box No. and Ship Date 3. Fragile Caution



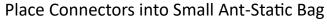




your BEST camera module partner

Sample Order Package Solution

Place Sample into Small Anti-Static Bag









Sample Labels on the Small Bag 1. Camera Module or Connector Model 2. Shipping Date and Quantity 3. Caution







your BEST camera module partner

Connectors Large Order Package Solution

Connectors in a Wheel







The Wheel is Perfectly Fitting the Box

Connectors Box Ready for Shipment









your BEST camera module partner

Company Kai Lap Technologies (KLT)

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.





Limited Warranty

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, www.KaiLapTech.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequential events.

















your BEST camera module partner

KLT Strength

Powerful Factory





Professional Service







Promised Delivery











